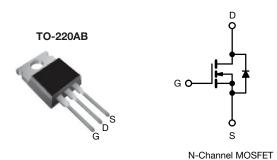


Power MOSFET



| PRODUCT SUMMA | RY | |
|--------------------------|------------------------|-----|
| V _{DS} (V) | 900 |) |
| $R_{DS(on)}(\Omega)$ | V _{GS} = 10 V | 8.0 |
| Q _g max. (nC) | 38 | |
| Q _{gs} (nC) | 4.7 | |
| Q _{gd} (nC) | 21 | |
| Configuration | Sing | le |

FEATURES

- Dynamic dV/dt rating
- Repetitive avalanche rated
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

| ORDERING INFORMATION | |
|---------------------------------|----------------|
| Package | TO-220AB |
| Lead (Pb)-free | IRFBF20PbF |
| Lead (Pb)-free and halogen-free | IRFBF20PbF-BE3 |

| PARAMETER | | | SYMBOL | LIMIT | UNIT |
|---|-------------------------|---|-----------------|-------|----------|
| Drain-source voltage | | V _{DS} | 900 | V | |
| Gate-source voltage | | | V_{GS} | | ± 20 |
| Continuous drain current | V -+ 10 V | $T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$ | | 1.7 | |
| Continuous drain current | V _{GS} at 10 V | T _C = 100 °C | I _D | 1.1 A | |
| Pulsed drain current ^a | | I _{DM} | 6.8 | 7 | |
| Linear derating factor | | | | 0.43 | W/°C |
| Single pulse avalanche energy b | | E _{AS} | 180 | mJ | |
| Repetitive avalanche current a | | | I _{AR} | 1.7 | Α |
| Repetitive avalanche energy ^a | | | E _{AR} | 5.4 | mJ |
| Maximum power dissipation T _C = 25 °C | | P_D | 54 | W | |
| Peak diode recovery dV/dt ^c | | | dV/dt | 1.5 | V/ns |
| Operating junction and storage temperature range | | T _J , T _{stg} | -55 to +150 | °C | |
| Soldering recommendations (peak temperature) d For 10 s | | | 300 | | |
| Mauring town | 6-32 or M3 screw | | | 10 | lbf ⋅ in |
| Mounting torque | | | | 1.1 | N⋅m |

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 117 mH, R_g = 25 Ω , I_{AS} = 1.7 A (see fig. 12)
- c. $I_{SD} \le 1.7$ A, $dI/dt \le 70$ A/ μ s, $V_{DD} \le 600$, $T_{J} \le 150$ °C
- d. 1.6 mm from case



Vishay Siliconix

| THERMAL RESISTANCE RAT | INGS | | | |
|-------------------------------------|-------------------|------|------|------|
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
| Maximum junction-to-ambient | R _{thJA} | - | 62 | |
| Case-to-sink, flat, greased surface | R _{thCS} | 0.50 | - | °C/W |
| Maximum junction-to-case (drain) | R _{thJC} | - | 2.3 | |

| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
|---|-----------------------|--|--|------|-----------|----------------------|------------------|
| Static | | • | | | | | |
| Drain-source breakdown voltage | V _{DS} | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ | | 900 | - | - | V |
| V _{DS} temperature coefficient | $\Delta V_{DS}/T_{J}$ | Reference | e to 25 °C, I _D = 1 mA | - | 1.1 | - | V/°C |
| Gate-source threshold voltage | V _{GS(th)} | V _{DS} = | · V _{GS} , I _D = 250 μA | 2.0 | - | 4.0 | V |
| Gate-source leakage | I _{GSS} | | V _{GS} = ± 20 V | - | - | ± 100 | nA |
| | | V _{DS} = | $V_{DS} = 900 \text{ V}, V_{GS} = 0 \text{ V}$ | | - | 100 | μΑ |
| Zero gate voltage drain current | I _{DSS} | V _{DS} = 720 V, V _{GS} = 0 V, T _J = 125 °C | | - | - | 500 | |
| Drain-source on-state resistance | R _{DS(on)} | V _{GS} = 10 V | I _D = 1.0 A ^b | - | - | 8.0 | Ω |
| Forward transconductance | 9 _{fs} | V _{DS} = | = 100 V, I _D = 1.0 A | 0.60 | - | - | S |
| Dynamic | | | | | | • | |
| Input capacitance | C _{iss} | $V_{GS} = 0 V$ | | - | 490 | - | pF |
| Output capacitance | C _{oss} | | $V_{DS} = 25 \text{ V},$ | | 55 | - | |
| Reverse transfer capacitance | C _{rss} | f = 1.0 MHz, see fig. 5 | | - | 18 | - | |
| Total gate charge | Qg | | | - | - | 38 | nC |
| Gate-source charge | Q _{gs} | V _{GS} = 10 V | $I_D = 1.7 \text{ A}, V_{DS} = 360 \text{ V},$ see fig. 6 and 13 b | - | - | 4.7 | |
| Gate-drain charge | Q _{gd} | | | =. | - | 21 | |
| Turn-on delay time | t _{d(on)} | | | - | 8.0 | - | |
| Rise time | t _r | V_{DD} = 450 V, I_{D} = 1.7 A, R_{g} = 18 Ω , R_{D} = 280 Ω , see fig. 10 ^b | | =. | 21 | - | ns |
| Turn-off delay time | t _{d(off)} | | | =. | 56 | - | |
| Fall time | t _f | | | - | 32 | - | |
| Gate input resistance | R _g | f = 1 MHz, open drain | | 0.6 | - | 3.4 | Ω |
| Internal drain inductance | L_{D} | 6 mm (0.25 | Between lead, 6 mm (0.25") from | | 4.5 | - | nH |
| Internal source inductance | L _S | package and center of die contact | | - | 7.5 | - |] |
| Drain-Source Body Diode Characteristic | es | | | | | | |
| Continuous source-drain diode current | I _S | MOSFET sym showing the | MOSFET symbol showing the | | - | 1.7 | A |
| Pulsed diode forward current ^a | I _{SM} | integral reverse p - n junction diode | | - | - | 6.8 | |
| Body diode voltage | V _{SD} | $T_J = 25 ^{\circ}\text{C}, I_S = 1.7 \text{A}, V_{GS} = 0 \text{V}^{ \text{b}}$ | | - | - | 1.5 | V |
| Body diode reverse recovery time | t _{rr} | T _ 05 °C 1 | - 1 7 A dl/dt - 100 A/··· | - | 350 | 530 | ns |
| Body diode reverse recovery charge | Q _{rr} | $T_J = 25 ^{\circ}\text{C}, I_F = 1.7 \text{A}, dI/dt = 100 \text{A}/\mu\text{s}$ | | - | 0.85 | 1.3 | nC |
| Forward turn-on time | t _{on} | Intrinsic turn-on time is negligible (turn-on is d | | | minated b | y L _S and | L _D) |

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width $\leq 300~\mu s;$ duty cycle $\leq 2~\%$



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

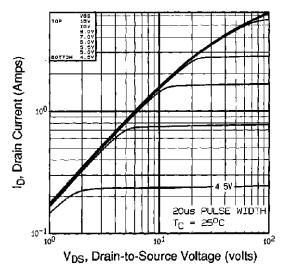


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

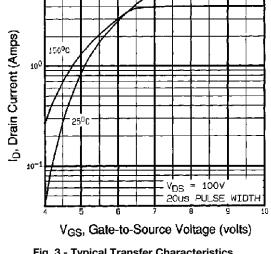


Fig. 3 - Typical Transfer Characteristics

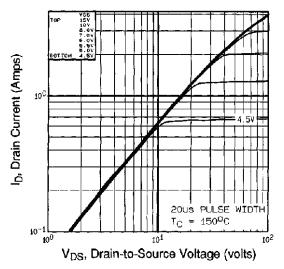


Fig. 2 - Typical Output Characteristics, $T_C = 150$ °C

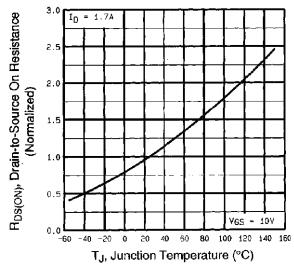


Fig. 4 - Normalized On-Resistance vs. Temperature



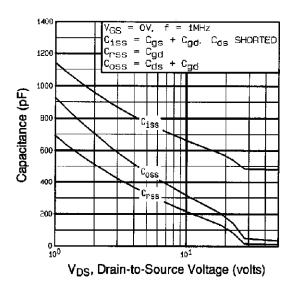


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

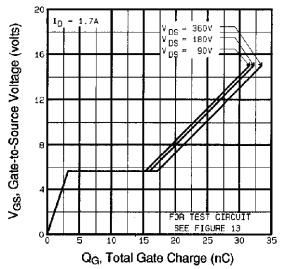


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

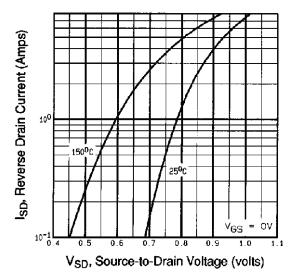


Fig. 7 - Typical Source-Drain Diode Forward Voltage

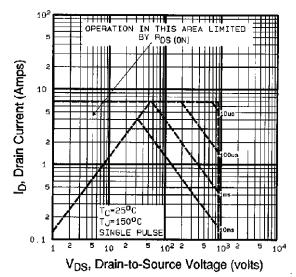


Fig. 8 - Maximum Safe Operating Area



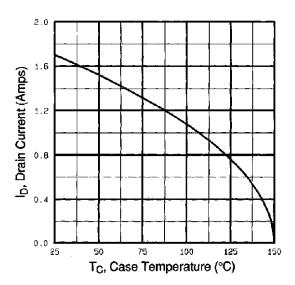


Fig. 9 - Maximum Drain Current vs. Case Temperature

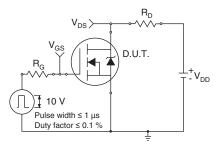


Fig. 10a - Switching Time Test Circuit

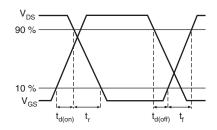


Fig. 10b - Switching Time Waveforms

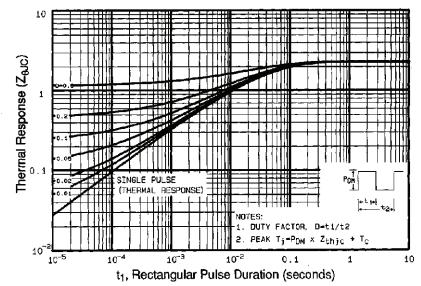


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

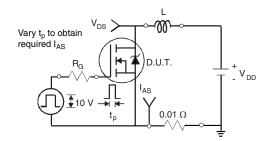


Fig. 12a - Unclamped Inductive Test Circuit

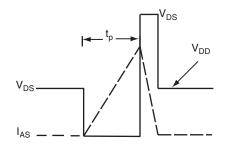


Fig. 12b - Unclamped Inductive Waveforms



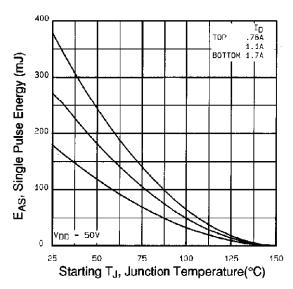


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

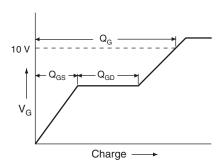


Fig. 13a - Basic Gate Charge Waveform

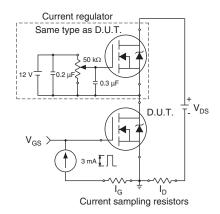
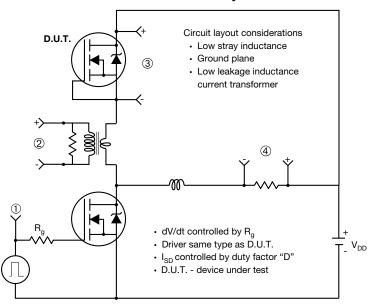


Fig. 13b - Gate Charge Test



Peak Diode Recovery dV/dt Test Circuit



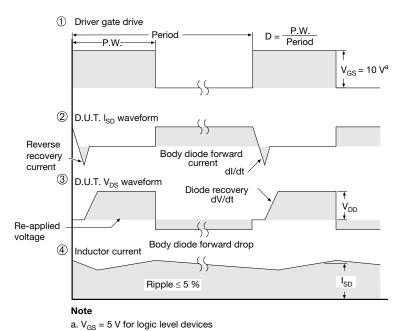


Fig. 14 - For N-Channel

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TO-220-1



| DIM. | MILLIM | METERS | INCHES | |
|------|--------|--------|--------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| Α | 4.24 | 4.65 | 0.167 | 0.183 |
| b | 0.69 | 1.02 | 0.027 | 0.040 |
| b(1) | 1.14 | 1.78 | 0.045 | 0.070 |
| С | 0.36 | 0.61 | 0.014 | 0.024 |
| D | 14.33 | 15.85 | 0.564 | 0.624 |
| Е | 9.96 | 10.52 | 0.392 | 0.414 |
| е | 2.41 | 2.67 | 0.095 | 0.105 |
| e(1) | 4.88 | 5.28 | 0.192 | 0.208 |
| F | 1.14 | 1.40 | 0.045 | 0.055 |
| H(1) | 6.10 | 6.71 | 0.240 | 0.264 |
| J(1) | 2.41 | 2.92 | 0.095 | 0.115 |
| L | 13.36 | 14.40 | 0.526 | 0.567 |
| L(1) | 3.33 | 4.04 | 0.131 | 0.159 |
| ØP | 3.53 | 3.94 | 0.139 | 0.155 |
| Q | 2.54 | 3.00 | 0.100 | 0.118 |

Note

DWG: 6031

• $M^* = 0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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